50 A, 650 V Hybrid IGBT

Using the novel field stop 4th generation IGBT technology and the 1.5th generation SiC Schottky Diode technology, VMAX016001 offers the optimum performance with both low conduction and switching losses for high efficiency operations in various applications, especially totem pole bridgeless PFC and Inverter.

Features

- AEC-Q101 Qualified
- Maximum Junction Temperature : $T_I = 175^{\circ}C$
- Positive Temperature Co-efficient for Easy Parallel Operating
- High Current Capability
- Low Saturation Voltage: $V_{CE(Sat)} = 1.6 \text{ V (Typ.)} @I_C = 50 \text{ A}$
- Fast Switching
- Tighten Parameter Distribution
- No Reverse Recovery/No Forward Recovery

Typical Applications

- Automotive
- On & Off Board Chargers
- DC-DC Converters
- PFC
- Industrial Inverter

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector to Emitter Voltage		650	V
Gate to Emitter Voltage Transient Gate to Emitter Voltage	V _{GES}	±20 ±30	V
Collector Current $@T_C = 25^{\circ}C$ $@T_C = 100^{\circ}C$	IC	100 50	Α
Pulsed Collector Current (Note 1)	I_{LM}	200	Α
Pulsed Collector Current (Note 2)	I _{CM}	200	Α
Diode Forward Current @T _C = 25°C @T _C = 100°C	lF	40 20	Α
Pulsed Diode Maximum Forward Current	I _{FM}	200	Α
Maximum Power Dissipation @T _C = 25°C @T _C = 100°C	PD	268 134	W
Operating Junction / Storage Temperature Range	TJ, TSTG	±55 to +175	°C
Maximum Lead Temp. for Soldering Purposes, 1/8" from case for 5 seconds	TL	300	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

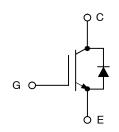
- 1. V_{CC} = 400 V, V_{GE} = 15 V, I_{C} = 200 A, R_{G} = 26 Ω , Inductive Load, 100% Tested.
- 2. Repetitive Rating: pulse width limited by max. Junction temperature.

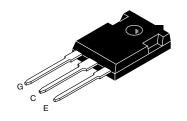


ON Semiconductor®

www.onsemi.com

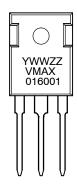
50 A, 650 V V_{CESat} = 1.6 V (Typ.)





TO-247-3L CASE 340CX

MARKING DIAGRAM



YWW = 3-Digit Data Code

ZZ = 2-Digit Lot Traceability Code

VMAX016001 = Specific Device Code

ORDERING INFORMATION

Device	Package	Shipping
VMAX016001	TO-247-3L	30 Units / Rail

THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal resistance junction-to-case, for IGBT	$R_{ heta JC}$	0.63	°C/W
Thermal resistance junction-to-case, for Diode	$R_{ heta JC}$	1.55	°C/W
Thermal resistance junction-to-ambient	$R_{ hetaJA}$	40	°C/W

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise noted)

Parameter	Test Conditions	Symbol	Min.	Тур.	Max.	Unit
OFF CHARACTERISTICS						
Collector-emitter breakdown voltage, gate-emitter short-circuited	V _{GE} = 0 V, I _C = 1 mA	BV _{CES}	650	_	-	V
Temperature Coefficient of Breakdown Voltage	$V_{GE} = 0 V$, $I_C = 1 \text{ mA}$	$\frac{\Delta BV_{CES}}{\Delta T_{J}}$	_	0.6	-	V/°C
Collector-emitter cut-off current, gate-emitter short-circuited	V _{GE} = 0 V, V _{CE} = 650 V	I _{CES}	-	-	250	μΑ
Gate leakage current, collector-emitter short-circuited	V _{GE} = 20 V, V _{CE} = 0 V	I _{GES}	-	-	±400	nA
ON CHARACTERISTICS						
Gate-emitter threshold voltage	$V_{GE} = V_{CE}$, $I_C = 50 \text{ mA}$	V _{GE(th)}	3.4	4.9	6.4	V
Collector-emitter saturation voltage	V_{GE} = 15 V, I_{C} = 50 A V_{GE} = 15 V, I_{C} = 50 A, T_{J} = 175°C	V _{CE(sat)}	-	1.6 1.9	2.1 -	V
DYNAMIC CHARACTERISTICS				•		
Input capacitance	V _{CE} = 30 V,	C _{ies}	-	3098	-	pF
Output capacitance	V _{GE} = 0 V, f = 1 MHz	C _{oes}	-	265	-	
Reverse transfer capacitance	1	C _{res}	-	9	-	
Gate charge total	V _{CE} = 400 V,	Q_g	-	94	-	nC
Gate to emitter charge	I _C = 50 V, V _{GE} = 15 V	Q _{ge}	-	18	-	
Gate to collector charge		Q _{gc}	-	23	-	
SWITCHING CHARACTERISTICS						
Turn-on delay time	T _J = 25°C	t _{d(on)}	=	17.6	-	ns
Rise time	VCC = 400 V, IC = 12.5 A	t _r	=	6.4	-	1
Turn-off delay time	$R_G = 4.7 \Omega$ $V_{GE} = 15 V$	t _{d(off)}	=	94.4	-	1
Fall time	Inductive Load	t _f	=	14.4	-	1
Turn-on switching loss	1	E _{on}	=	131	-	μJ
Turn-off switching loss	1	E _{off}	=	96	-	1
Total switching loss	1	E _{ts}	=	227	-	1
Turn-on delay time	T _J = 25°C	t _{d(on)}	-	19.2	-	ns
Rise time	$VCC = 400 \text{ V},$ $IC = 25 \text{ A}$ $R_G = 4.7 \Omega$ $V_{GE} = 15 \text{ V}$ Inductive Load	t _r	-	11.2	-	
Turn-off delay time		td _(off)	-	89.6	-	
Fall time		t _f	-	6.4	-	1
Turn-on switching loss		Eon	-	311	-	μJ
Turn-off switching loss		Eoff	_	141	-	1
Total switching loss		Ets	-	452	-	

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

Parameter	Test Conditions	Symbol	Min.	Тур.	Max.	Unit
SWITCHING CHARACTERISTICS					•	
Turn-on delay time	T _J = 175°C	t _{d(on)}	-	16	_	ns
Rise time	VCC = 400 V, IC = 12.5 A	t _r	_	8	_	
Turn-off delay time	$R_G = 4.7 \Omega$ $V_{GE} = 15 V$	t _{d(off)}	_	107.2	_	
Fall time	Inductive Load	t _f	-	53.6	_	
Turn-on switching loss		E _{on}	-	157	-	μJ
Turn-off switching loss		E _{off}	-	193	-	
Total switching loss		E _{ts}	-	350	-	
Turn-on delay time	T _J = 175°C	t _{d(on)}	-	17.6	-	ns
Rise time	VCC = 400 V, IC = 25 A	t _r	-	14.4	-	
Turn-off delay time	$R_G = 4.7 \Omega$ $V_{GE} = 15 V$	t _{d(off)}	-	99.2	-	
Fall time	Inductive Load	t _f	-	9.6	-	
Turn-on switching loss		E _{on}	-	350	-	μJ
Turn-off switching loss		E _{off}	-	328	-	
Total switching loss		E _{ts}	-	678	-	
DIODE CHARACTERISTICS						
Forward voltage	I _F = 20 A I _F = 20 A, T _J = 175°C	V _F	_	1.45 1.83	1.75 -	V
Total Capacitance	V _R = 400 V, f = 1 MHz	С	-	103	-	pF
	V _R = 600 V, f = 1 MHz	1	-	99	-	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS

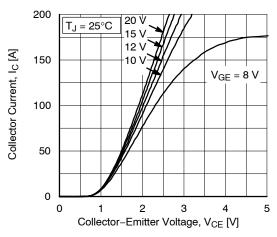


Figure 1. Typical Output Characteristics $(T_J = 25^{\circ}C)$

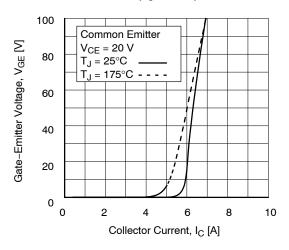


Figure 3. Transfer Characteristics

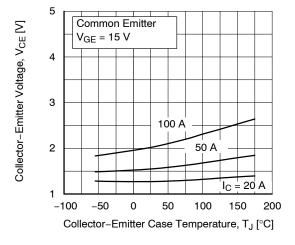


Figure 5. Saturation Voltage vs. Case Temperature at Variant Current Level

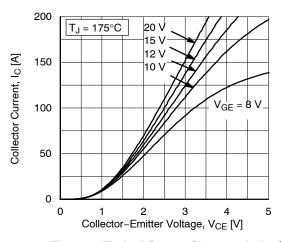


Figure 2. Typical Output Characteristics "
(T_J = 175°C)

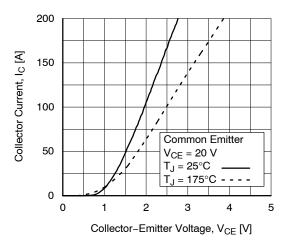


Figure 4. Typical Saturation Voltage Characteristics

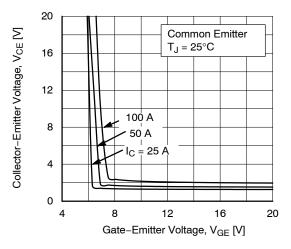


Figure 6. Saturation Voltage vs. V_{GE} ($T_J = 25^{\circ}C$)

TYPICAL CHARACTERISTICS (continued)

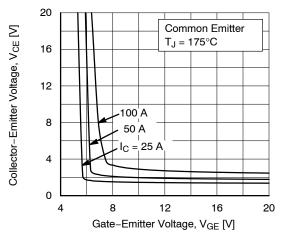


Figure 7. Saturation Voltage vs. V_{GE} (T_J = 175°C)

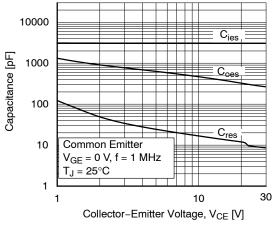


Figure 8. Capacitance Characteristics

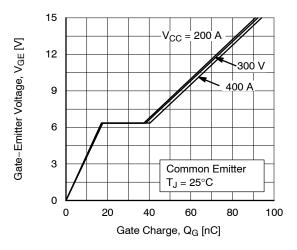


Figure 9. Gate Charge Characteristics $(T_J = 25^{\circ}C)$

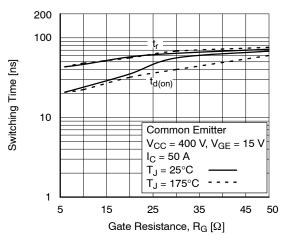


Figure 10. Turn-on Characteristics vs. Gate Resistance

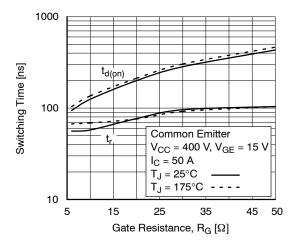


Figure 11. Turn-Off Characteristics vs. Resistance

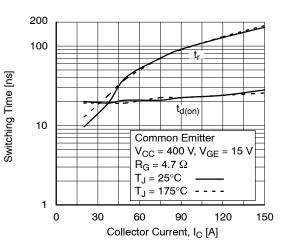


Figure 12. Turn-On Characteristics vs. Collector Current

TYPICAL CHARACTERISTICS (continued)

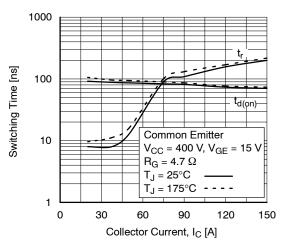


Figure 13. Turn-Off Characteristics vs. Collector Current

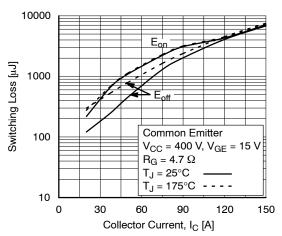


Figure 15. Switching Loss vs. Collector Current

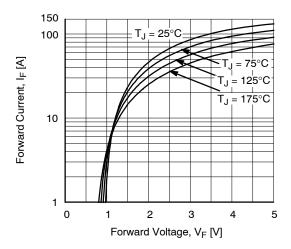


Figure 17. (Diode) Forward Characteristics vs. (Normal I–V)

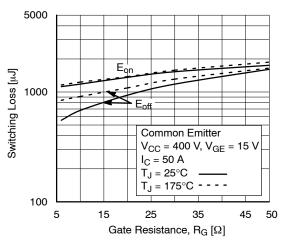


Figure 14. Switching Loss vs. Gate Resistance

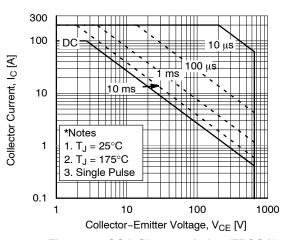


Figure 16. SOA Characteristics (FBSOA)

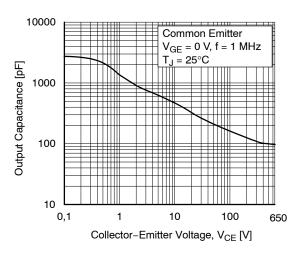


Figure 18. (Diode) Output Capacitance (C_{oes}) vs. Reverse Voltage

TYPICAL CHARACTERISTICS (continued)

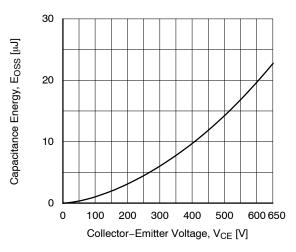


Figure 19. Output Capacitance Stored Energy

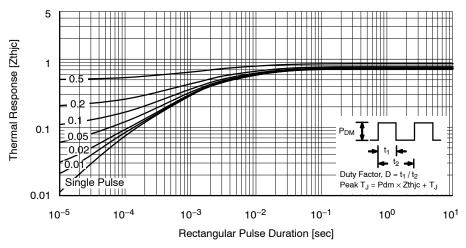


Figure 20. Transient Thermal Impedance of IGBT

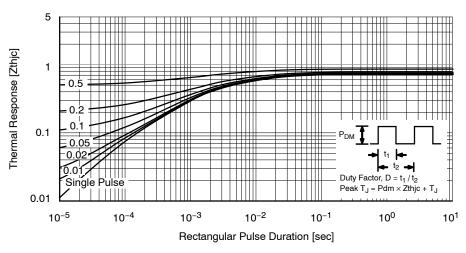
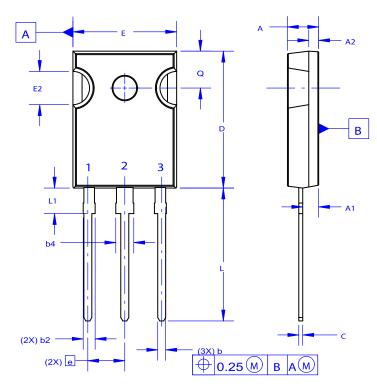


Figure 21. Transient Thermal Impedance of Diode

PACKAGE DIMENSIONS

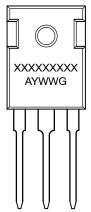
TO-247-3LD CASE 340CX ISSUE O



NOTES: UNLESS OTHERWISE SPECIFIED.

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 2009.
- D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.

GENERIC MARKING DIAGRAM*

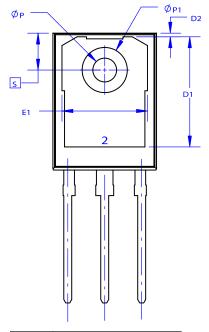


XXXXX = Specific Device Code

A = Assembly Location Y = Year

WW = Work Week
G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " •", may or may not be present. Some products may not follow the Generic Marking.



DIM	MIL	MILLIMETERS				
DIM	MIN	NOM	MAX			
Α	4.58	4.70	4.82			
A 1	2.20	2.40	2.60			
A2	1.40	1.50	1.60			
D	20.32	20.57	20.82			
Е	15.37	15.62	15.87			
E2	4.96	5.08	5.20			
е	~	5.56	~			
L	19.75	20.00	20.25			
L1	3.69	3.81	3.93			
ØΡ	3.51	3.58	3.65			
Q	5.34	5.46	5.58			
S	5.34	5.46	5.58			
b	1.17	1.26	1.35			
b2	1.53	1.65	1.77			
b4	2.42	2.54	2.66			
С	0.51	0.61	0.71			
D1	13.08	~	~			
D2	0.51	0.93	1.35			
E1	12.81	~	~			
ØP1	6.60	6.80	7.00			

ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hol

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800–282–9855 Toll Free USA/Canada

Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910 ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative